# **APPROVAL**

PART NO.	DESCRITION	REMARKS
HT2403L	LCD MODULE (240 × RGB × 320 Dots)	* ROHS compliant

CUSTOMER APPLICATION P/N	
APPROVED BY	
DATE	

PLEASE KINDLY FIND AND APPROVE THE SPECIFICATIONS INSERTED HEREIN AND RETURN ONE COPY HERE OF WITH YOUR SIGNATURE OF APPROVAL.

PERPARED BY	CHECKED BY	CONFIRMED BY



### HYES Optoelectronics, Inc.

2000 Wyatt Drive Suite 6 Santa Clara, CA 95054 USA

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# **REVISION HISTORY**

	- N		
Date	Rev. No.	Page	Summary
Aug. 26, 2008	-	ALL	- 1'st Issue

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# 1. Basic Specfications

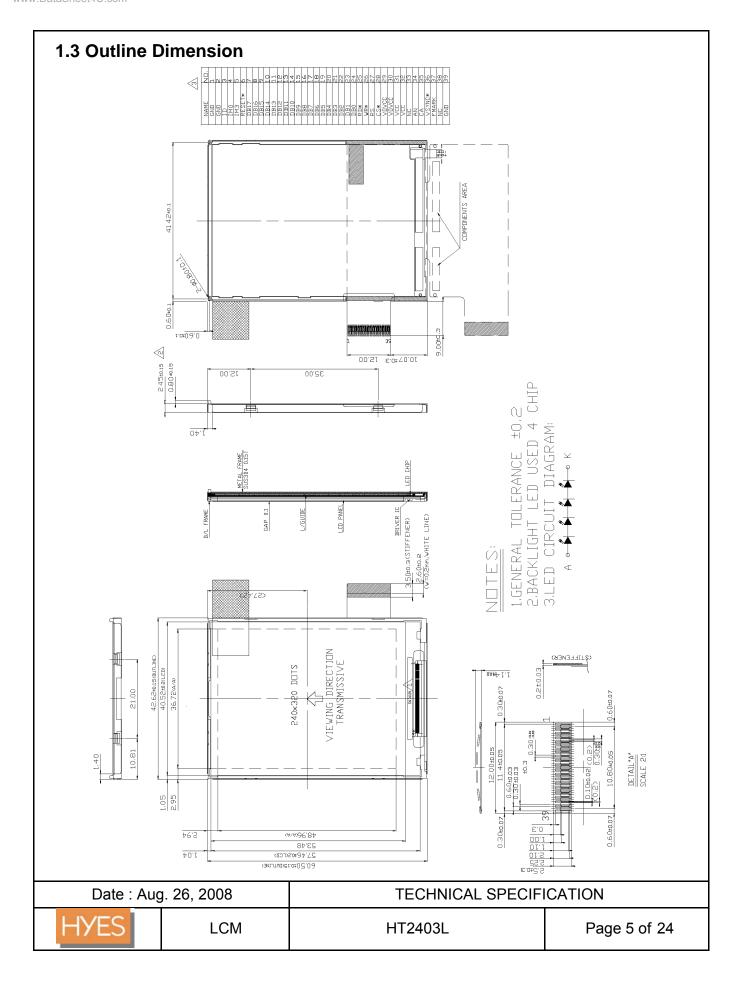
## 1.1 Display Specifications

The play openioanone		
ltem	Description	Note
Resolution	240 × RGB × 320	
Display mode	TFT, Normally White, Transmissive	
Viewing direction	6 O'clock	
Driving method	720Ch-Source, 320Ch-Gate	
Backlighting	LED, White (4 chips in Serial)	
Diver IC	S6D1121, COG	
Others	80-Series, 18/16/9/8-Bit Parallel	

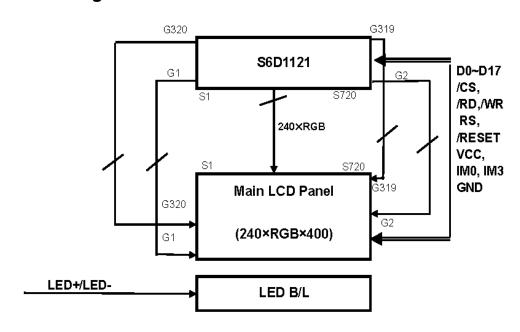
# **1.2 Mechanical Specifications**

ltem	Specification	Unit
Module Size (W × H × T)	42.62 × 60.5 × 2.45	mm
Viewing Area (W × H)	-	mm
Active Area (W × H)	36.72 × 48.96	mm
Dot Size (W × H)	-	mm
Dot Pitch (W × H)	0.051 × 0.153	mm
Weight	About 10	g

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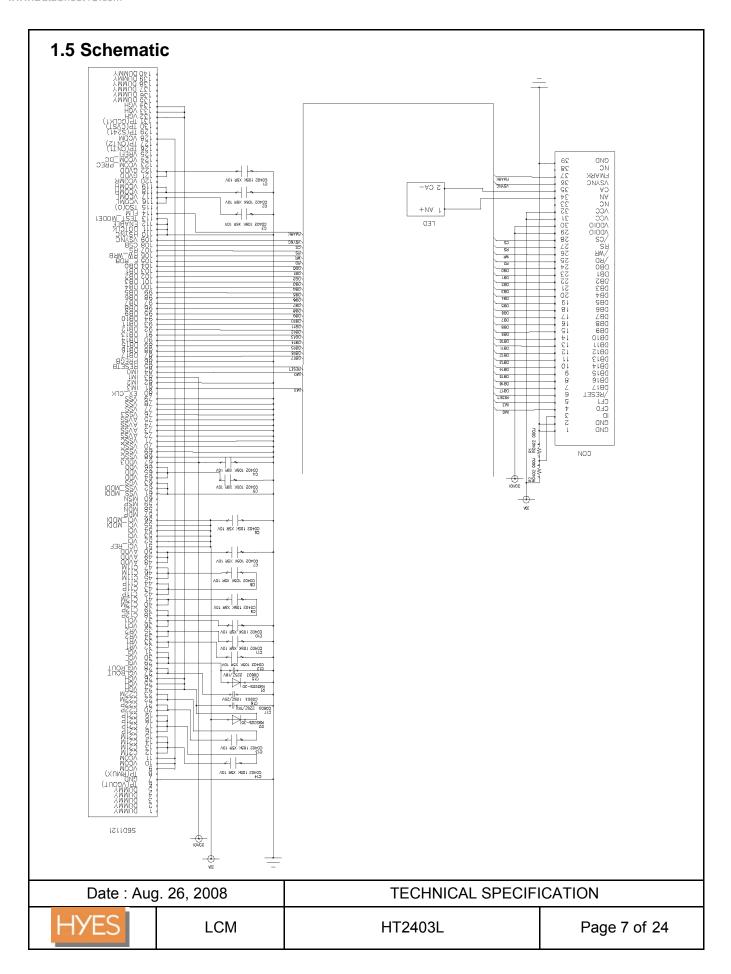


# 1.4 Block Diagram



CF0 Interface Dat		Datebus
0	18-bit interface	DB17-DB0
1	9-bit interface	DB17-DB9
0	16-bit interface	DB17-DB10,DB8-DB1
1	8-bit interface	DB17-DB10
	0 1 0 1	1 9-bit interface 0 16-bit interface

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### 2. Electrical Characteristics

### 2.1 Absolute Maximum Ratings

ltom	Cymbol		Value		Unit	Condition	Domork	
Item		Symbol	Min.	Тур.	Max	Offic	Condition	Remark
Supply	Logic	VDDIO	-0.3	-	5.0	٧	Ta =25℃	
Voltage Range	Power Supply	VCC	-0.3	-	5.0	٧	Ta =25℃	
	LCD	VGH-VGL	-0.3	-	35.0	٧	Ta =26℃	
Input Volta	age	V <sub>IN</sub>	-0.3	-	VCC+0.5	V	Ta =25℃	

### 2-2 Environmental Conditions

Item	Symbol			Max.	Unit
Operating temperature	Topr -20		70	°C	
Storage temperature	Tstg	-30		80	°C
Humidity (Ambient temperature=Ta)	Ta ≤ 60	°C		90% RH max.	

### 2-3 DC Characteristics

Itoms	Items			Spec. Value		Unit	Condition
items		Sysbol	MiN.	Тур.	Max.	Offic	Condition
	Ligic	VDDIO	1.65	1.8	3.3	V	
Operating Voltage	Power Supply	VCC	1.65	2.8	2.88	٧	
Operating voltage	GATE	VGH	7.5	1	18	V	Note1)
	GATE	VGL	-11	-	-5.5	V	Note i)
Supply our	0		-	9.5	14.3	mA	Note2)
Supply current		ICC					
Input voltage	High level	V <sub>IH</sub>	0.8 × V <sub>CC</sub>	-	V <sub>cc</sub>	V	-
input voitage	Low level	$V_{\rm IL}$	0	-	0.2 × V <sub>CC</sub>	V	-

Note1) The value can be adjusted by software to optimize display quality.

Note2) Display black

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# 3. Optical Characteristics

Transmissive mode

(Ta = 25℃)

Ite	em	Symbol		Min.	Тур.	Max.	Unit	Condition	Note
Viousin		θ2- <del>0</del> 1	Ø=0 (Y1-Y2)		60	-	Dog	Cr > 10	
Viewir	ig	02-01	Ø=90 (X1-X2)	80	90	-	Deg	CI > 10	
Contra	st ratio	Cr		200	380	-	ı	$\theta = 0$ $\emptyset = 0$	
Respon	se Time		Tr + Tf	-	25	40	ms	$\theta = 0$ $\emptyset = 0$	
CIE	R		(x,y)	0.58, 0.30	0.62, 0.34	0.68, 0.38			
Coordi	G		(x,y)	0.28, 0.55	0.32, 0.59	0.38, 0.63		θ = 0	
- nate	В		(x,y)	0.01, 0.04	0.14, 0.08	0.18, 0.12		Ø = 0	
	W		(x,y)	0.24, 0.26	0.28, 0.30	0.32, 0.34			
Brigh	tness		L	230	290	-	cd/m2	18mA/LED	
Unifo	rmity			70	1	-			

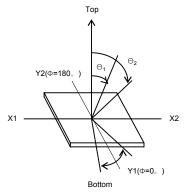
<sup>\*</sup>  $\emptyset$  = 0°,  $\emptyset$  = 90° means viewing direction.

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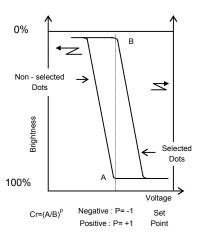
<sup>\*</sup> B/L is turned on.

<sup>\*</sup> Remark : as for contrast ratio, it is measured in panel only.

Note 1 . Definition of angle  $\Theta$  and  $\Phi$ 

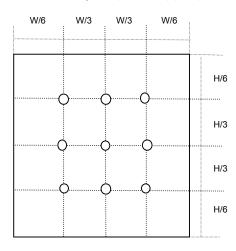


Note 3. Definition of contrast Cr

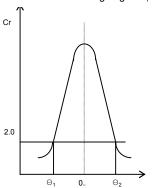


Lens Ø = 3mm

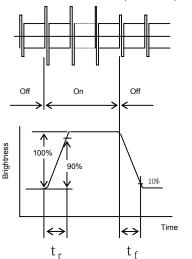
Note 5. Measuring Point(9 POINTS) (WxH)



Note 2. Definition of viewing angle  $\, \Theta_1$  and  $\, \Theta_2$ 



Note 4. Definition of Optical response



Rating is defined as the average brightness inside the viewing area

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### 4. Interface Pins

No.	symbol	Description			
1	GND	Ground			
2	GND	Ground			
3	ID	ID bit setting of device ID code			
4	CF0	CPU Interface Mode Selection(IM0)			
5	CF1	CPU Interface Mode Selection(IM3)			
6	RESET	RESET signal(low active)			
7	DB17	Data Bus (Instruction & Display Data)			
8	DB16	Data Bus (Instruction & Display Data)			
9	DB15	Data Bus (Instruction & Display Data)			
10	DB14	Data Bus (Instruction & Display Data)			
11	DB13	Data Bus (Instruction & Display Data)			
12	DB12	Data Bus (Instruction & Display Data)			
13	DB11	Data Bus (Instruction & Display Data)			
14	DB10	Data Bus (Instruction & Display Data)			
15	DB9	Data Bus (Instruction & Display Data)			
16	DB8	Data Bus (Instruction & Display Data)			
17	DB7	Data Bus (Instruction & Display Data)			
18	DB6	Data Bus (Instruction & Display Data)			
19	DB5	Data Bus (Instruction & Display Data)			
20	DB4	Data Bus (Instruction & Display Data)			
21	DB3	Data Bus (Instruction & Display Data)			
22	DB2	Data Bus (Instruction & Display Data)			
23	DB1	Data Bus (Instruction & Display Data)			
24	DB0	Data Bus (Instruction & Display Data)			
25	RD	Read Signal			
26	WR	Write Signal			
27	RS	Data/command identif icasion			
28	cs	Chip Select			
29	VDDIO	Power Supply for Interface (1.8V)			
30	VDDIO	Power Supply for Interface (1.8V)			
31	VCC	Power Supply for Analog and Logic (2.8V)			
32	VCC	Power Supply for Analog and Logic (2.8V)			
33	NC	No connection			
34	AN	Power Supply for LED			
35	CA	GND for LED			
36	VSYNC	Frame synchronous signal			
37	FMARK	Frame head pulse signal			
38	NC	No connection			
39	GND	Ground			

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# 5. Backlight Specfication (LED Unit)

Item	Symbol	Spec. Value			Unit	Condition
item	Symbol	Min.	Тур.	Max.	Onit	Condition
Real Current	I <sub>LED</sub>	-	18	20	mA	note 1.
Power dissipation	$P_{D}$	-	-	160	mW	note 2.
Operation temp.	Topr		- 20 ~ 70		${\mathbb C}$	-
Storage temp.	Tstr		- 30 ~ 80		${\mathbb C}$	-

Note 1. B/L: 4EA LED in Serial, the typical current is 18mA (full brightness).

Note2. Total power consumpation (max) depends on LED current/ LED driver efficiency, etc.

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### 6. Recommended Software Setting Values (Initial code)

#### LDI:S6D1121

	REG NO	VALUE			
	0011	1D04			
	0012	0033			
P	0013	CC00			
0	0015	382E			
W	0014	002A			
E R	0013	CC04(DELAY 10ms)			
Ι.	0013	CC06(DELAY 50ms)			
0	0013	CC4F(DELAY 10ms)			
Ň	0013	674F			
	0011	1D02			
	0030	0100			
G A	0031	220E			
M	0032	211F			
M	0033	2423			
Α	0034	2628			
R	0035	3127			
	0036	211E			
S	0037	1723			
E	0038	0F15			
T	0039	0A0A			
i	003A	1315			
N	003B	3619			
G	003C	0102			
	003D	0000			
	0016	0006			
	0001	0127			
	0002	0013			
0	0003	0003			
T	8000	0208			
Н	000A	0507			
E	000B	0000			
R	000C	0003			
М	0041	0000			
O	0050	0000			
D	0060	0005			
Ē	0070	000B			
	0071	0000			
	0078	0000			
	0079	0000 0000(DELAY 50mg)			
	007A	0000(DELAY 50ms)			

	REG NO	VALUE
	0007	0051(DELAY 50)ms
D	0007	0053(DELAY 20)ms
N S	0020	0000
P	0021	0000
<u> </u>	0022	

#### Standby on sequence

Display off sequence						
0007	0052(DELAY 40ms)					
0007	0050					
0007	0010					
Power off se	Power off sequence					
0012	0000					
0013	CC46(DELAY 50ms)					
0013	CC44(DELAY 50ms)					
0013	CC40					
set standby	mode					
0010	0001					

#### Standby off sequence

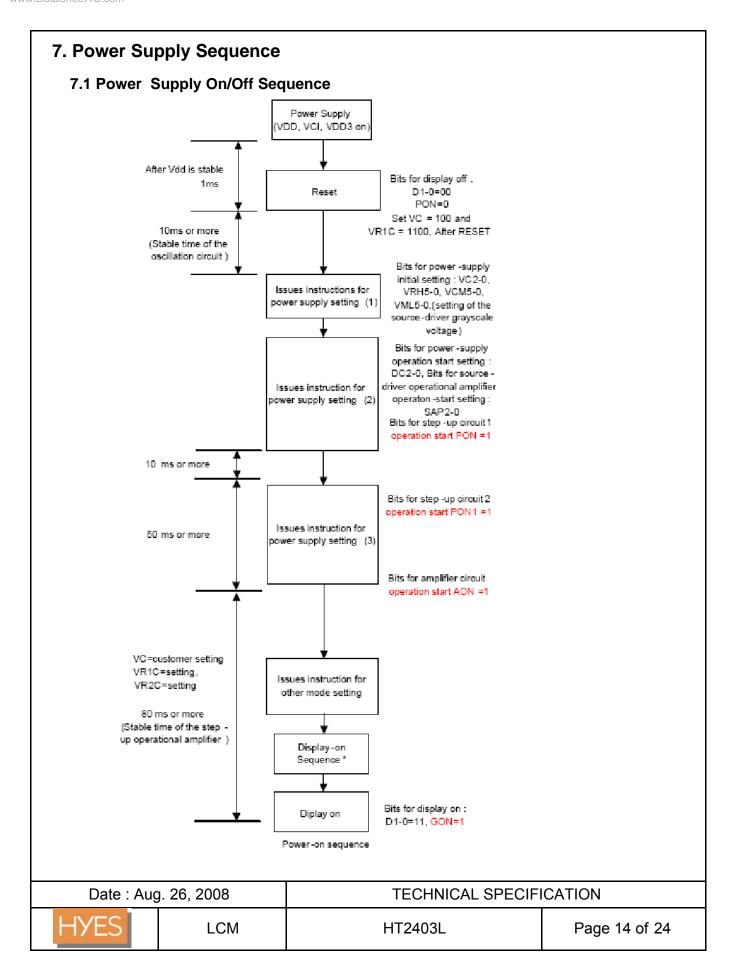
0004	2501(DELAY 20ms)				
0010	0000(DELAY 20ms)				
Call power on sequence					
Call display on sequence					

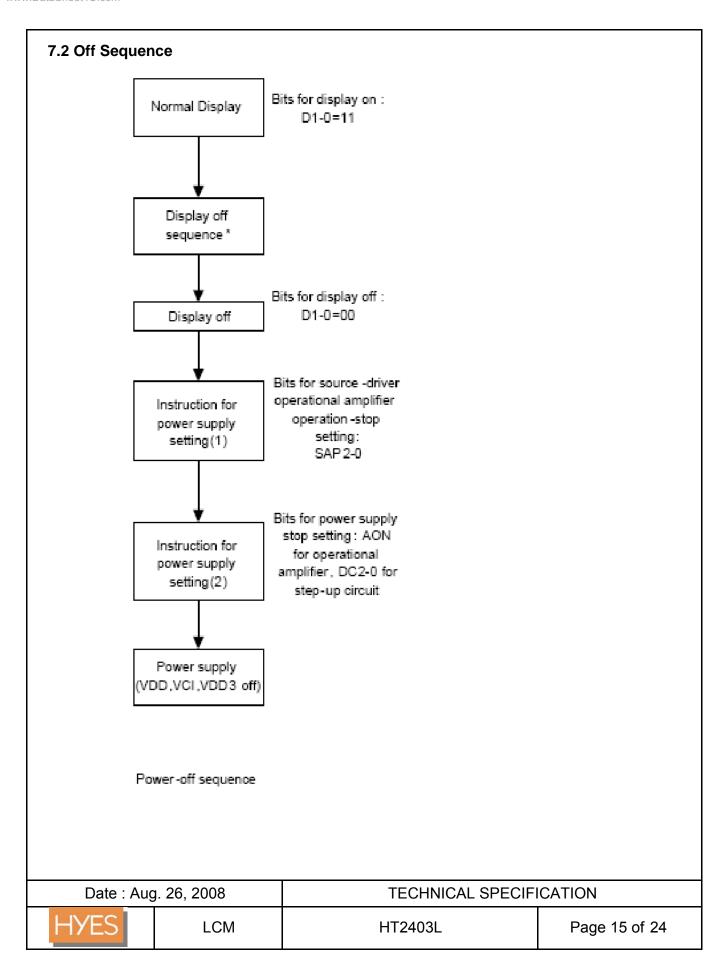
#### Partial display sequence

0007							
0042	the end of 1st screen						
0043	the start of 1st screen						
0044	the end of 2nd screen						
0045	the start of 2nd screen						
DELAY 50ms	DELAY 50ms						
0007	4153						
Return to ful	l display						
0042	013F						
0043	0000						
0044	013F						
0045	0000						
END							

NOTE: HYES requires the customer to follow the above instructions strictly. If customer would like to change the above instructions, the customer should inform HYES and get re-check from HYES, or the customer will be responsible for any unexpected result because of the change.

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## 8. Read/Write Timing characteristics (80 series MPU)

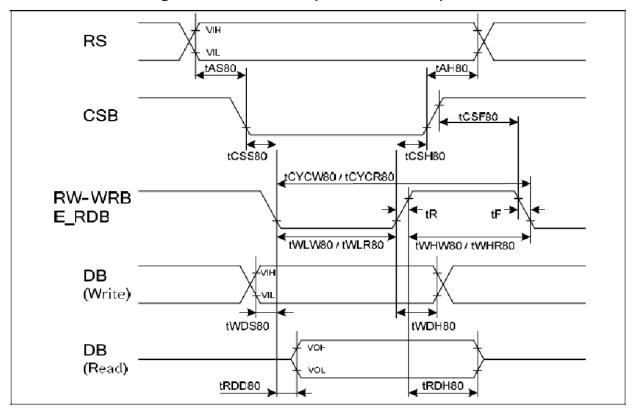


Figure 8.3.2.1 AC Timing Parameter and Timing Diagram of 80-system interface

Table 8.3.2.1 AC Timing Characteristics

(VDD = 1.5 V, VDD3 = 1.65 to 3.3V,  $T_A$  = -40 to +85 °C)

		(	10 1, 1220 110		
Parameter	Symbol	Condition	Min.	Max.	Unit
Address setup time	tAS80	RS ~ CSB	5	-	ns
Address hold time	tAH80	R3 ~ C3B	5	-	ns
Chip select setup time	tCSS80	OOD DW WDD	5	-	ns
Chip select holed time	tCSH80	CSB ~ RW_WRB CSB ~ E RDB	5	-	ns
Chip select wait time	tCSF80	CSB~E_KDB	10	-	ns
Write enable period	tCYCW80		65	-	ns
Write enable low pulse width	tWLW80	RW_WRB	22.5	-	ns
Write enable high pulse width	tWHW80	107_770	22.5	-	ns
Read enable period	tCYCR80		400	-	ns
Read enable low pulse width	tWLR80	E_RDB	190	-	ns
Read enable high pulse width	tWHR80		190	-	ns
Write data setup time	tWDS80	DD DW WDD	5	-	ns
Write data hold time	tWDH80	DB ~ RW_WRB	5	-	ns
Read data delay time	tRDD80	DD E DDD	10	-	ns
Read data hold time	tRDH80	DB ~ E_RDB	10	-	ns
Rising time	tR	All 1	-	160	ns
Falling time	tF	All signals	5	40	ns

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### **Reset Timing characteristics**

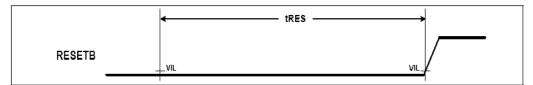


Figure 8.6.1 AC Timing Parameter and Timing Diagram of RESET

#### Table 8.6.1 AC Characteristics of RESET

(VDD = 1.5 V, VDD3 = 1.65 to 3.3V, T<sub>A</sub> = .40 to +85 °C)

Characteristic	Symbol	Min.	Max.	Unit
Reset low pulse width	tRES	15	-	us

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### 9. LCD Module Out-Going Quality Level

#### (1.0) Purpose

The LCD specification provides outgoing provision and its expected quality level based on our outgoing inspection of LCD.

#### (2.0) Applicable Scope

The LCD specification is applicable to the arrangement in regard to outgoing Inspection and quality assurance after it.

#### (3.0) Quality Specification

#### (3.1) Quality Level

The quality level of HYES are based on GB/T2828.1, Apply Level II,

normal inspection by single sampling.

Rank	Item	AQL	Note
Major(MA)	Segment Short, Missing	0.65	
	Solder Bridging, Cold Solder		
	Outside Dimension		
Minor (MI)	Black Spots, White Spots, Foreign Substance,	1.0	
	Pinhole, Segment Deformation, Scratchs(Glass & Pol.)		
	Air Bubbles between Glass & Polarizer,		
	Color Variation, Solder Ball, Misalignment		

Note) AQL- Acceptable Quality Level

#### (3.2) Appearance Standards

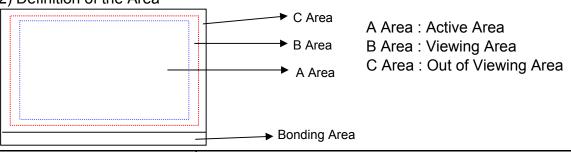
#### 1) Inspection Conditions

The LCD shall be inspected under 20W white fluorescent lamp light.

The distance between the eyes and the sample shall be 30cm.

All directions for inspecting the sample should be within 30° to perpendicular line.

#### 2) Definition of the Area



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Vо	Item		Criteria					Remark
1	Segment Short Segment Missing	Not allowe	d				Rank MA	
2	Solder Bridging		_	n component			MA	
_	0 : 11 D1 1			it, is not allo			3.66	
3	Outside Dimension	_	_	ion must be	within		MA	
_	0.110.11	permitable					1	
4	Cold Solder	Cold solde		wed.			MA	
5	Black(White) Spots, Foreign	1) Round T	уре				MI	¥
	Substances	Ai	rea	Accepta	ıble Q'ty	Remark		<del>         </del>
		Dime:	nsion**	A Area	B Area	1		M 1
				Ign	iore			
		≪		2	Ignore	1		
				1	Ignore	1		** : Mean
		0.3 <		0	Ignore	1		Diameter
		2) Liner Ty		Aggente	abla O'ts:	D omark		(X+Y)/2
		I	ension		ible Q'ty	Remark		
		Length	Width	A Area	B Area			
		-	≤ 0.025		iore			
		≤ 2.5	≤ 0.05	3	Ignore			
		≤ 1.5	≤0.075	2	Ignore			
		At (1) & (	•	fect q'ty is n	ound type nust not			
5	OC Spot						MI	
	_	A	rea	Accepta	ıble Q'ty	Remark		
		Dime	nsion**	A Area	B Area	1		
		$\leq$	0.2	Ign	ore			
			0.8	3	Ignore	1		
		€	1.0	1	Ignore	1		
					. <u> </u>			
7	Air Bubles						MI	
7	Air Bubles Between Glass &	A	rea	Accepta	ıble Q'ty	Remark	MI	
7			rea nsion**	Accepta A Area	ıble Q'ty B Area	Remark	MI	
7	Between Glass &	Dime		A Area		Remark	MI	
7	Between Glass & Polarizer	Dime:	nsion** 0.15	A Area	B Area iore	Remark	MI	
7	Between Glass & Polarizer	Dime	nsion** 0.15 0.3	A Area Ign	B Area nore Ignore	Remark	MI	
7	Between Glass & Polarizer	Dime: ≤	0.15 0.3 0.5	A Area Ign 3	B Area nore Ignore Ignore	Remark	MI	
7	Between Glass & Polarizer	Dime	nsion*** 0.15 0.3 0.5 0.7	A Area Ign 3	B Area nore Ignore Ignore Ignore	Remark	MI	
7	Between Glass & Polarizer	Dime	0.15 0.3 0.5	A Area Ign 3 2	B Area nore Ignore Ignore	Remark	MI	

No	Item		Criteria	Rank	Remark
8	Pin hole		$(X+Y)/2 \le 0.2 \text{ mm}$	MI	TOMAIN
	(On Segment)		Within 1 per one	1411	
	(On Segment,		segment (Less than 0.1mm		
			- · ·		
		Total das	X  is not counted)		
		1 otal del	ects q'ty is must not exceed 5 pieces.		
9	Segment			MI	(X + Y)/2
	Deformation		* A		≤ 0.2mm
			$(X+Y)/2 \le 0.2 mm$		
			$A \leq 0.2  \mathrm{mm}$		
			$B \leq 0.2 \text{ nm}$		
		<u> </u>	$(C-D) \leq 0.2 \text{mm}$		
			(C-D) = 0.2mm		
		_			
		-	<u> </u>		
			Acceptable Q'ty	7	
		Do	ot, Segment 1	7 I	
			LCD 5	7	
			≤ 0.1 Ignore all defect	7	
		Each visible	le dot must be more than half	<b>-</b>	
			effective dot area		
10	Color Variation		three colors, except LCD	MI	
	Color Fullwich		olor is acceptable.	1,11	
11	Glass & Polarizer	_	0.5(2) condition	MI	
11	Scratch	TOHOW NC	7.5(2) <b>c</b> ondition	1011	
12	Solder Ball	1) A contai	ole if the size of void is less	MI	
12	Solder Dali	than 0.18		1011	
		2)Acceptat	ple if a solder ball is not movable		
		3)Rejectab	le if the solder ball exceed		
		1 ' -	$.54 \times 2.54\mathrm{mm}$ area.		
13	Miss Alignment		ple if it dose not exceed 50% of		
1.5	IVII33 / MIGHIICIL	the lead			
		ule lead			
		_   <del>_ </del>			
		₩	X > W/2 : Reject		
		<del></del>	X		
			LEAD		
		1 ' -	le, provided that it does		
			0% of the component		
		terminati	on width.		
		VW1	<b>I</b> ₩22		
		A Austr			
		-			
			W1 > W2 : Reject		
	Nists . A limitation some	ole is given top r	priority		
	Note: A limitation samp	,, o , o 9, , o, , , o b k			
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### (3.3) Appearance Spec

Item			Criteri	a		Rank	Remark
14 Touch Panel	1) Round Ty	1) Round Type . Foreign Substances				MI	
					,		Y
		rea	Accepta		Remark		
		ısion**	A Area	B Area			
		0.1	Ign				
	≤	0.2	2	Ignore	]		
	≤ 0		1	Ignore			** : Mean
	0.3 <		0	Ignore			Diameter
							(X+Y)/2
	2) Liner Typ	e & Scratcl	1				
	Dime	nsion	Accepta	ble Q'ty	Remark		
	Length	Width	A Area	B Area	1		
	-	W≤0.025	Ign				
	L≤3.0		Ign		1		
	3.0 <l≤5.0< td=""><td>W≤0.05</td><td>2</td><td></td><td>Ignore</td><td></td><td></td></l≤5.0<>	W≤0.05	2		Ignore		
	€ 7	W≤0.1	1		1 -0 1		
	-	W>0.1	Follow ro		1		
	It's NG.	e Newton :			the touch panel the touch panel		

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### (4.0) Reliability Condition

Item	Content	
Room Temperature Operation	50,000 hrs	

### (4.1) Reliability Test - Module Middle Reliability

No.	Item	Condition	Test	Sample	Creteria	Note
			Time	Numbers	(Acc/Rej)	
1	High Temp	70 ± 2°C	120 hrs	3	0/1	
	Operation					
2	Low Temp	-20 ± 2℃	120 hrs	3	0/1	
	Operation					
3	High Humidity	00°C	120 hrs	3	0/1	
	Storage	90%rh				
4	Thermal	30mn stage -20℃	100 cycles	3	0/1	
	Shock	↔70°C	/6days			

### (4.2) Criteria

- a. No changes for indication and appearance.
- b. Leave the all samples under roon temperature 4 hours after reliability test ends.

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### 10. LCD Module Operation Instruction

#### Part I. How to use the LCD Module

- 1. Don't hit the LCD Panel in any way because the LCD is made of glass.
- 2. Don't clean the surface of LCD with hard things. Please clean LCD with Air-gun or very soft cloth when necessary. The protective film on the POL can be removed just before assembly, otherwise, dust, spit or other foreign matter may attached on the LCD under the protective film. After the protective film is removed, only air-gun can be used to remove any dust or foreign matter. Fingure or cloth MUST NOT be used in such cases.
- 3. No chemical liquid is allowed to clean the LCD, such as alcohol, acetone and IPA. All of these candamage the LCD. Water on the LCD must be cleaned as soon as possible, for it will cause POL color change or other defect.
- 4. Please move and assemble LCD very carefully during assembly, and don't push or twist it.
- 5. Don't damage the FPC of LCD module. It will cause permanent defect.
- 6. Don't disassemble LCD module. It will cause permanent defect.
- 7. Don't expose LCD module under sunshine, strong fluorescence or ultraviolet radiation.
- 8. Please make sure that operators wear static-protective bands effectively and working tables are effectively earthing during operation.
- 9. Please place LCD module on the tray provided by HYES while moving it, in order to avoid mechanical damage. Hold the module's side frames to avoide damage during moving.
- 10. Don't twist, disassemble, squeeze or hit the PCB. It will damage the circuit or component on PCB and cause functional defect.
- 11. Please use the connector according to the instruction provided by HYES.
- 12. Please place dual module with the sub-panel upward. Trays should be placed in contrary direction. An empty tray should be placed on the top.
- 13. Sealing operation on PCB must be very careful to avoid short or cut the original circuit on PCB.Otherwise, it will cause permenant damage to the LCD.
- 14. Don't add direct DC or high voltage to LCD panel. It will cause functional damage to the LCD or shorten the life of LCD product.
- 15. LCD may respond slowly or display abnormally in extrem temperature (lower than -20℃ or higher than 50℃). But this doesn't mean LCD functional defect. LCD will display normally in regular temperature. Therefore, don't use LCD product in extrem temperature.

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- 16. Don't push the display area of LCD panel, it will cause abnormal display. This doesn't mean LCD functional defect, neither. LCD will display normally in regular temperature.
- 17. Electrical test of LCD product is made by using mobile phone provided by Customer. We can use special test equipment to do the test, also.
- 18. The black band on IC on LCD product is used to protect the IC from light. Please do NOT remove it.
- 19. Please take great care to use connector. Customer should be responsible for connector defect caused by operation on Customer side.

#### Part II Storage

- 1. Physical status of liquid crystal will change in extrem temperature, and it can not be resumed whenthe temperature returns to be normal. So LCD module should be stored in required temperature.
- 2. LCD module should be stored in required humidity. Low hymidity may add static, while high humidity may corrode the ITO circuit of LCD product. The suitable storage environment is: temperature:22±5°C, humidity: 55%±10%.
- 3. Don't expose LCD module under sunshine, strong fluorescence or ultraviolet radiation for a long time.lt should be stored in dark area.
- 4. LCD should be stored in static-protective polythene bag. Don't expose it in the air for a long time.

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